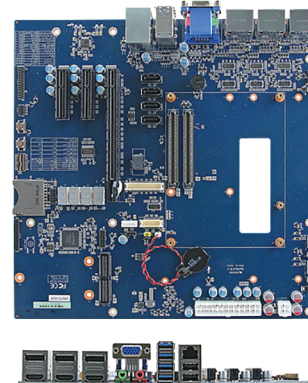


* This is an OEM Only Product

Features

- Micro ATX Form Factor
- PICMG® COM Express® Revision 3.0 & supports COM Express Type 6 compatible CPU Modules
- Supports VGA, LVDS, eDP, HDMI, DisplayPort
- Supports Mic-in, Line-out audio interfaces
- 1 x PCIe x16, 2 x PCIe x4 Slots
- 4 x SATA III, 4 x USB 3.1(10Gbps), 4 x USB 2.0, 1 x LAN, 1 x SDIO, 1 x IET



Specifications

External I/O	
Expansion	2 x PCIe x4 1 x PCIe x16 1 x SDIO/DIO (Optional) 1 x IET
USB	4 x USB 2.0, 4 x USB 3.1
SATA	4 x SATA III Onboard
Video	3 x DisplayPort 1 x VGA 3 x HDMI 1 x LVDS 1 x eDP
Audio	Mic-in, Line-out
LAN	1 x RJ45
DIO	1 x 8-bit GPIO
Mechanical and Environment	
Power Requirement	ATX
Power Type	ATX
Operating Temp	0 ~ 60°C (32 ~ 140°F)
Storage Temp	-40 ~ 85°C (-40 ~ 185°F)
Operating Humidity	40°C @ 95% Relative Humidity, Non-condensing
Form Factor	Micro ATX (uATX)
Dimensions	9.6" x 9.6" (243.84mm x 243.84mm)
Certification Information	CE, FCC Class B

Ordering Info

EEV-EX16-B1R Type 6 Micro ATX Carrier Board for COM Express Module Rev.3.0 A1. Check manual for accessories included in the package.

* All product specifications and images are subject to change without notice. Last update: 2021/05/09



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